



No-Clean flux IF 2005C

INTERFLUX®
ELECTRONICS N.V.



Technical data IF 2005C
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No-clean, halide free soldering flux

Description:

Interflux® IF 2005C is a low solids no-clean flux, especially developed for selective soldering in lead-free and SnPb applications. It is the version of the IF 2005-series with the largest process window in activity.

IF 2005C is also suitable for wave soldering but IF 2005K and IF 2005M are the first choice for respectively lead-free and SnPb wave soldering.

IF 2005C has excellent solderability with lead-free alloys and on virtually all finishes (NiAu, I-Sn, HAL, Cu-OSP,...). It is resistant to elevated preheat temperatures, and to long contact times with a higher working temperature. This makes IF 2005C the best choice for selective soldering.

This absolutely halide free flux meets the EN, Bellcore and IPC requirements. It is formulated to provide the best combination of solderability, ease of processing and highest reliability.

All flux components can evaporate during the soldering process. This means also the most safe no-clean flux for high-end electronics.

With no rosin nor resin to create sticky residue, there is nothing left behind after soldering to foul test pins or prevent electrical contact.

The flux is classified as OR/L0 according to EN and IPC standards.



Products pictured may differ from the product delivered

Physical properties

Appearance	Clear colourless liquid
Solid content	3,3% ± 0,3
Density at 20°C	0,813 g/ml — 0,815 g/ml
Water content	3-4%
Acid number	26 – 30 mg KOH/g
Flash point T.O.C	15°C (59°F)



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Key advantages:

- Absolutely halide free
- For lead-free and SnPb soldering
- Excellent for selective soldering
- Suitable for spray, drop jet, foam and dip fluxing
- Very high compatibility with conformal coatings



Application of the flux

1. Drop jet fluxing

Because no air is used, correct positioning of the nozzle underneath the holes is important. To check if enough flux has been applied on components with not enough through hole solder wetting, apply some flux on the top of the hole with a small brush. If better through hole wetting is achieved, increase the flux amount. In all cases try to apply the minimum flux amount that achieves good soldering results. The sprayed area is often

bigger than the soldered area, resulting in flux residues on the area that has not been soldered. Minimum flux application will reduce flux residues.

2. Spray fluxing:

It is advisable to use a double spray stroke during fluxing whenever possible and to keep the flux pressure low. The nozzle traverse speed is set to a value which ensures that every point on the board is sprayed twice, once from two different sides. When this condition is met the result is a 50%

overlap on the spray pattern. This will give the most uniform spray pattern coverage. Spray pattern coverage can be checked by passing a piece of cardboard through the spray fluxer. Remove it before it reaches the preheat unit. Additionally the spray fluxer settings need to be checked by passing a glass plate or empty circuit board through the fluxer. Remove it from the machine before it reaches the preheat unit and check it on flux quan-

tity. There can be no drops present. Drops are a sign of excessive flux and are difficult to evaporate. Reduce the flux amount until defects typical for a too low flux amount like, webbing, flagging, shorts and icicles are observed. From this point increase the flux level again until defects disappear.

3. Foam fluxing:

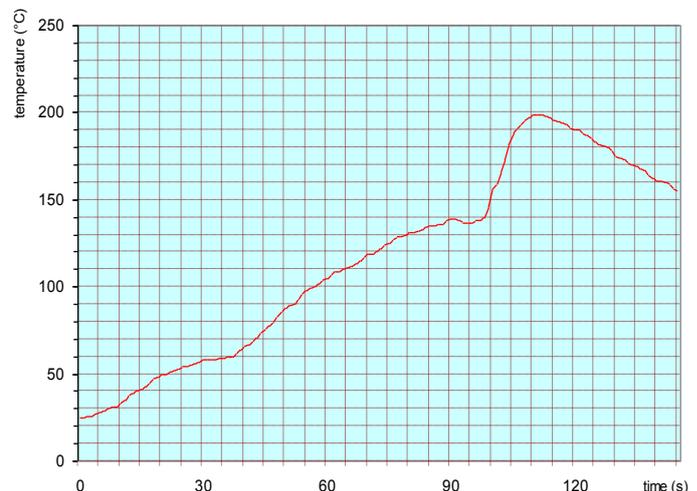
To ensure good foaming, the level of flux needs to be at least 2–3 cm over the porous flux stone. The use of an air knife is imperative.

Preheating

The recommended preheat T° is: 100 - 160°C. This value is retrieved from field experience. The flux can have lower preheat T° as long as the solvent is evaporated before wave contact. Preheat T° above 150°C are to be kept as short as possible in order to prevent flux

exhaustion. If possible, avoid hot air preheat settings above 150°C. Always take into account the physical properties of the board, components and soldering application in order to get an optimal final result .

Slope: 1-3°C/s



T° measured on the topside of the PCB on a lead-free soldering machine.

Wave contact

In selective soldering the wave contact is mostly determined by good through hole wetting. This is influenced by the preheating, the thermal mass

of PCB and component, the wettability of the finishes, the solidification point of the used alloy and the working temperature. Typical contact times

are between 1s and 2s. In wave soldering the same considerations apply, but other parameters like wave

type, carriers, board design, nitrogen,... are important. Typical contact times are between 2s and 4s.



White residues and cleaning

White residues

If white residues appear after soldering there can be several reasons. In selective soldering or wave soldering with selective soldering carriers, the area of flux application is often larger

than the area with wave contact. This might result in white residues. Also too much flux application, or condensation of flux vapours might cause white residues. These residues are safe. The residues are

not sticky and will not cause contact problems. Less flux application, more heat or more wave contact can reduce these residues. IF 2005M/ IF 2005K give less residues but have a smaller process win-

dow in activity.

Cleaning

The residues can be brushed away or evaporated with heat. The flux is cleanable with most conventional cleaning agents.

Handling

Storage

Store the flux in the original packaging, tightly sealed at a preferred temperature of +5° to +25°C

Safety

Please always consult the safety datasheet of the product.

Density control

The density of the IF 2005C flux shall be checked using a suitable density meter, the value showed by the density meter should be compared, after temperature compensation, with the value in the IF 2005C density table and may only be adjusted with the T 2005M accordingly.

Titration check

The solids content value of the IF 2005C flux can be determined by titration. The liquids for titration are available at Interflux. Adjustments of the solid content may only be done by using T 2005M conditioner.

Reuse

Do not mix used and fresh flux.

Test results

conform EN 61190-1-1(2002) and IPC J-STD-004B

Property	Result	Method
Chemical		
Flux designator	OR L0	J-STD-004B
Qualitative copper mirror	pass	J-STD-004B IPC-TM-650 2.3.32
Qualitative halide		
Silver chromate (Cl, Br)	pass	J-STD-004B IPC-TM-650 2.3.33
Quantitative halide	0,00%	J-STD-004B IPC-TM-650 2.3.35
Environmental		
SIR test	pass	J-STD-004B IPC-TM-650 2.6.3.7
Qualitative corrosion, flux	pass	J-STD-004B IPC-TM-650 2.6.15
ECM 40°C; 93% RH; 5 VDC	pass	Siemens Prüfprotokoll (2005)
EM, 50°C; 90% RH; 5VDC	pass	HP, EL-EN 861-00



Packaging:

IF 2005C is available in the following packages:

- 10 litres polyethylene drums
- 25 litres polyethylene drums
- 200 litres polyethylene drums

Trade name : IF 2005C No-Clean, Halide Free Soldering Flux

D i s c l i m e r

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